

MMSZ4xxxET1G Series, SZMMSZ4xxxET1G Series

Zener Voltage Regulators

500 mW SOD-123 Surface Mount

Three complete series of Zener diodes are offered in the convenient, surface mount plastic SOD-123 package. These devices provide a convenient alternative to the leadless 34-package style.

Features

- 500 mW Rating on FR-4 or FR-5 Board
- Wide Zener Reverse Voltage Range – 1.8 V to 43 V
- Package Designed for Optimal Automated Board Assembly
- Small Package Size for High Density Applications
- ESD Rating of Class 3 (> 16 kV) per Human Body Model
- Peak Power – 225 W (8 x 20 μ s)
- AEC-Q101 Qualified and PPAP Capable
- SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- Pb-Free Packages are Available*

Mechanical Characteristics:

CASE: Void-free, transfer-molded, thermosetting plastic case

FINISH: Corrosion resistant finish, easily solderable

MAXIMUM CASE TEMPERATURE FOR SOLDERING PURPOSES:

260°C for 10 Seconds

POLARITY: Cathode indicated by polarity band

FLAMMABILITY RATING: UL 94 V-0

MAXIMUM RATINGS

| Rating | Symbol | Max | Unit |
|---|-----------------|----------------|-------------|
| Peak Power Dissipation @ 20 μ s (Note 1) @ $T_L \leq 25^\circ\text{C}$ | P_{pk} | 225 | W |
| Total Power Dissipation on FR-5 Board, (Note 2) @ $T_L = 75^\circ\text{C}$ Derated above 75°C | P_D | 500 6.7 | mW mW/°C |
| Thermal Resistance, (Note 3) Junction-to-Ambient | $R_{\theta JA}$ | 340 | °C/W |
| Thermal Resistance, (Note 3) Junction-to-Lead | $R_{\theta JL}$ | 150 | °C/W |
| Junction and Storage Temperature Range | T_J, T_{stg} | -55 to +150 | °C |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Nonrepetitive current pulse per Figure 11.
2. FR-5 = 3.5 x 1.5 inches, using the minimum recommended footprint.
3. Thermal Resistance measurement obtained via infrared Scan Method.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

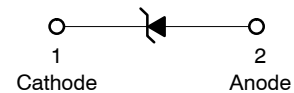


ON Semiconductor®

<http://onsemi.com>



SOD-123
CASE 425
STYLE 1



MARKING DIAGRAM



- xxx = Device Code (Refer to page 2)
- M = Date Code
- = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

| Device | Package | Shipping† |
|----------------|----------------------|-------------------------|
| MMSZ4xxxET1G | SOD-123 (Pb-Free) | 3,000 / Tape & Reel |
| SZMMSZ4xxxET1G | SOD-123 (Pb-Free) | 3,000 / Tape & Reel |
| MMSZ4xxxET3G | SOD-123 (Pb-Free) | 10,000 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

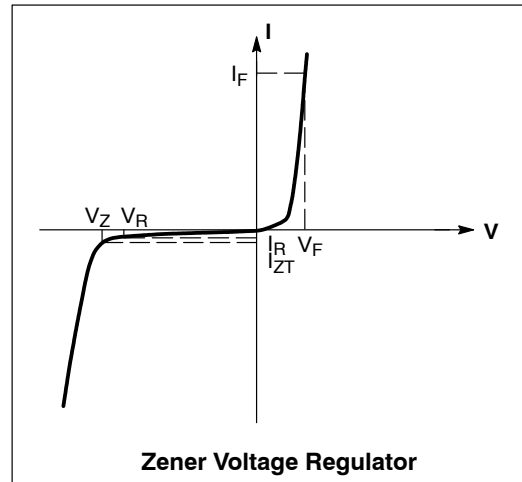
DEVICE MARKING INFORMATION

See specific marking information in the device marking column of the Electrical Characteristics table on page 2 of this data sheet.

MMSZ4xxxET1G Series, SZMMSZ4xxxET1G Series

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted, $V_F = 0.95\text{ V Max. @ } I_F = 10\text{ mA}$)

| Symbol | Parameter |
|----------|----------------------------------|
| V_Z | Reverse Zener Voltage @ I_{ZT} |
| I_{ZT} | Reverse Current |
| I_R | Reverse Leakage Current @ V_R |
| V_R | Reverse Voltage |
| I_F | Forward Current |
| V_F | Forward Voltage @ I_F |



ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted, $V_F = 0.9\text{ V Max. @ } I_F = 10\text{ mA}$)

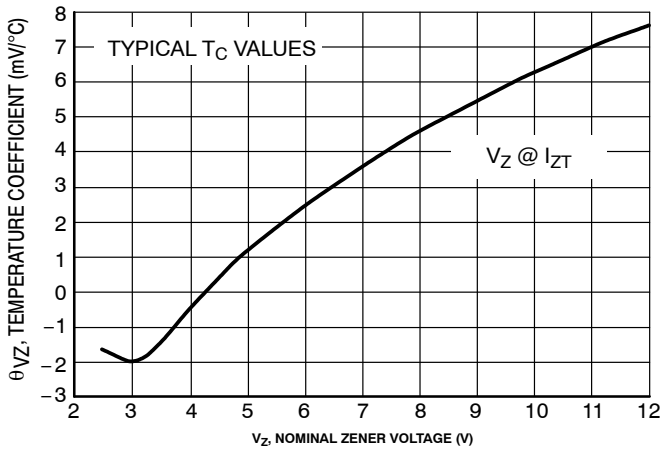
| Device* | Device Marking | Zener Voltage (Note 1) | | | | Leakage Current | |
|---------------------|----------------|------------------------|------------|-------------|---------------|-----------------|----------|
| | | V_Z (V) | | | @ I_{ZT} | I_R @ V_R | |
| | | Min | Nom | Max | μA | μA | V |
| MMSZ4680ET1G | CF8 | 2.09 | 2.2 | 2.31 | 50 | 4 | 1 |
| MMSZ4684ET1G | CG3 | 3.13 | 3.3 | 3.47 | 50 | 7.5 | 1.5 |
| MMSZ4688ET1G | CG7 | 4.47 | 4.7 | 4.94 | 50 | 10 | 3 |
| MMSZ4689ET1G | CG8 | 4.85 | 5.1 | 5.36 | 50 | 10 | 3 |
| MMSZ4690ET1G | CG9 | 5.32 | 5.6 | 5.88 | 50 | 10 | 4 |
| MMSZ4691ET1G | CH1 | 5.89 | 6.2 | 6.51 | 50 | 10 | 5 |
| MMSZ4692ET1G | CH2 | 6.46 | 6.8 | 7.14 | 50 | 10 | 5.1 |
| MMSZ4693ET1G | CH3 | 7.13 | 7.5 | 7.88 | 50 | 10 | 5.7 |
| MMSZ4697ET1G | CH7 | 9.50 | 10 | 10.50 | 50 | 1 | 7.6 |
| MMSZ4699ET1G | CH9 | 11.40 | 12 | 12.60 | 50 | 0.05 | 9.1 |
| MMSZ4701ET1G | CJ2 | 13.3 | 14 | 14.7 | 50 | 0.05 | 10.6 |
| MMSZ4702ET1G | CJ3 | 14.25 | 15 | 15.75 | 50 | 0.05 | 11.4 |
| MMSZ4703ET1G | CJ4 | 15.20 | 16 | 16.80 | 50 | 0.05 | 12.1 |
| MMSZ4705ET1G | CJ6 | 17.10 | 18 | 18.90 | 50 | 0.05 | 13.6 |
| MMSZ4709ET1G | CK1 | 22.80 | 24 | 25.20 | 50 | 0.01 | 18.2 |
| MMSZ4711ET1G | CK3 | 25.65 | 27 | 28.35 | 50 | 0.01 | 20.4 |
| MMSZ4717ET1G | CK9 | 40.85 | 43 | 45.15 | 50 | 0.01 | 32.6 |

1. Nominal Zener voltage is measured with the device junction in thermal equilibrium at $T_L = 30^\circ\text{C} \pm 1^\circ\text{C}$.

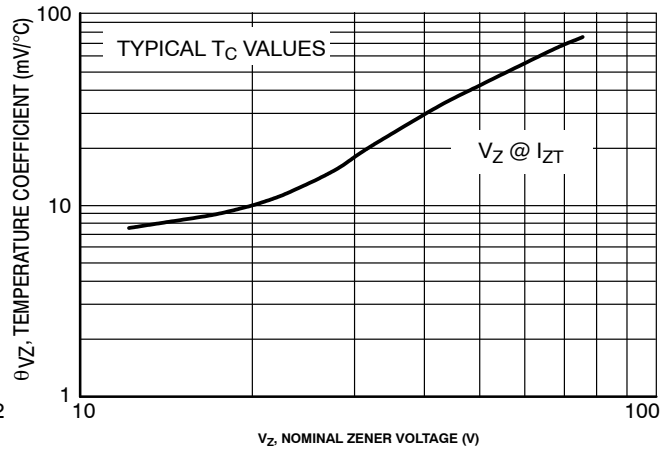
*Include SZ-prefix devices where applicable.

MMSZ4xxxET1G Series, SZMMSZ4xxxET1G Series

TYPICAL CHARACTERISTICS



**Figure 1. Temperature Coefficients
(Temperature Range -55°C to +150°C)**



**Figure 2. Temperature Coefficients
(Temperature Range -55°C to +150°C)**

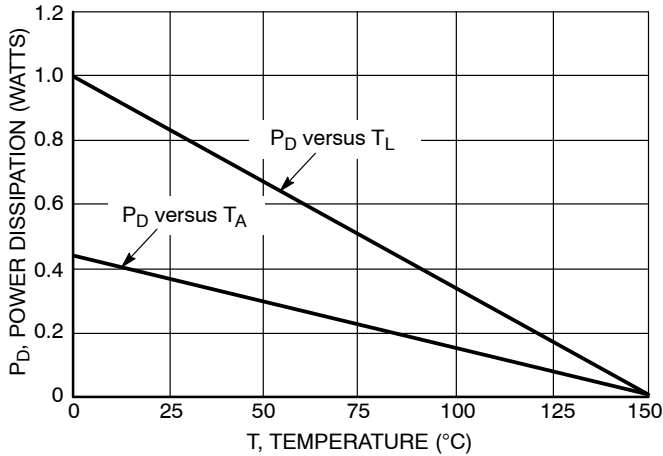


Figure 3. Steady State Power Derating

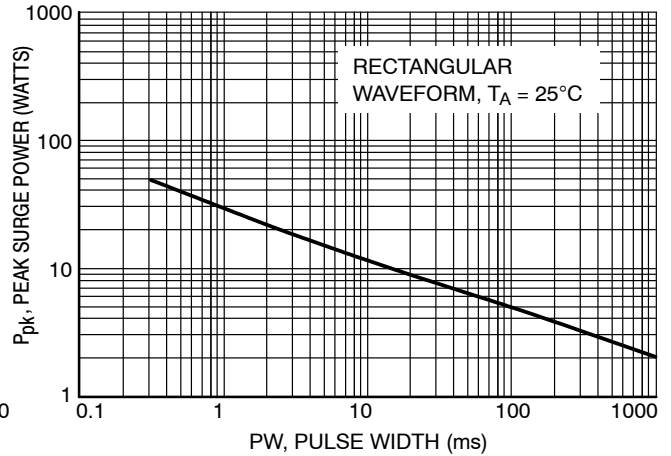
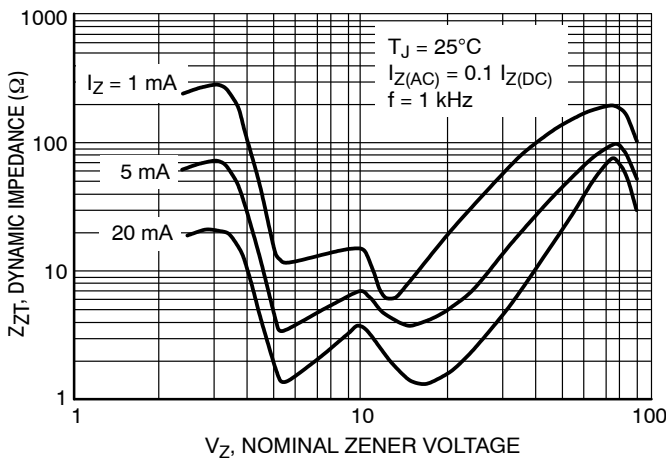


Figure 4. Maximum Nonrepetitive Surge Power



**Figure 5. Effect of Zener Voltage on
Zener Impedance**

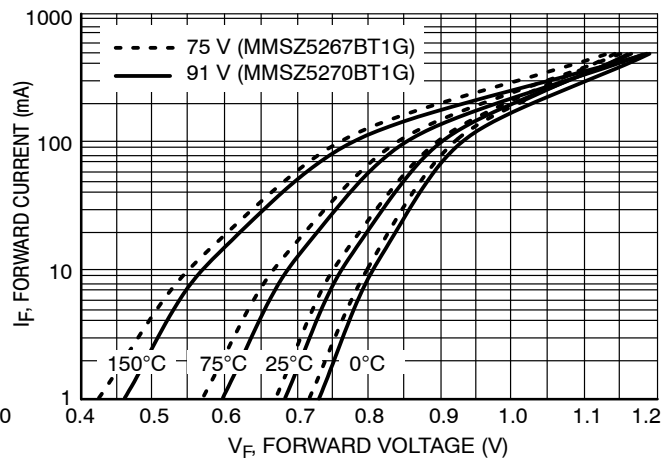


Figure 6. Typical Forward Voltage

TYPICAL CHARACTERISTICS

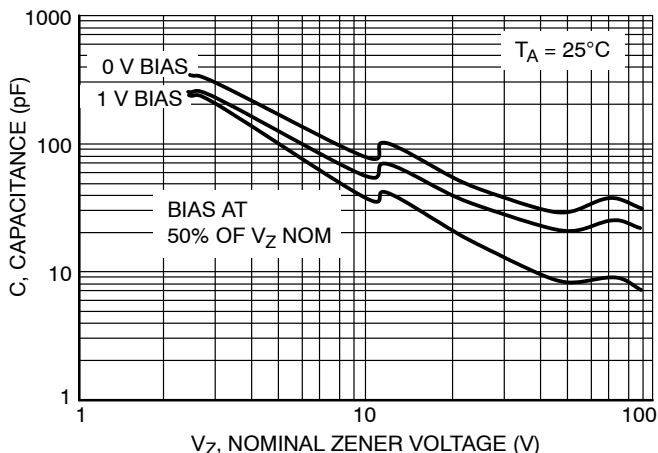


Figure 7. Typical Capacitance

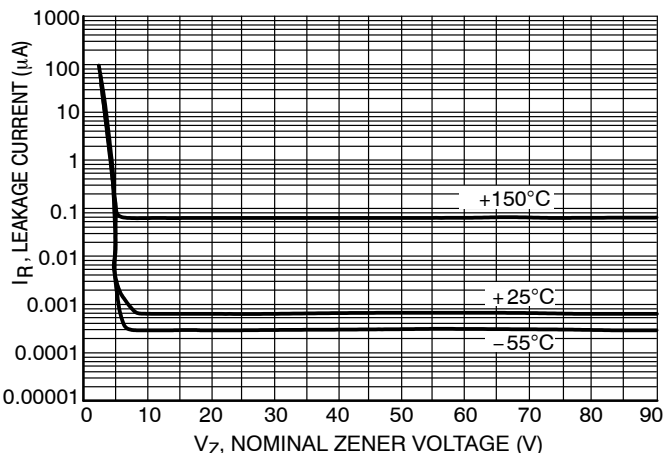


Figure 8. Typical Leakage Current

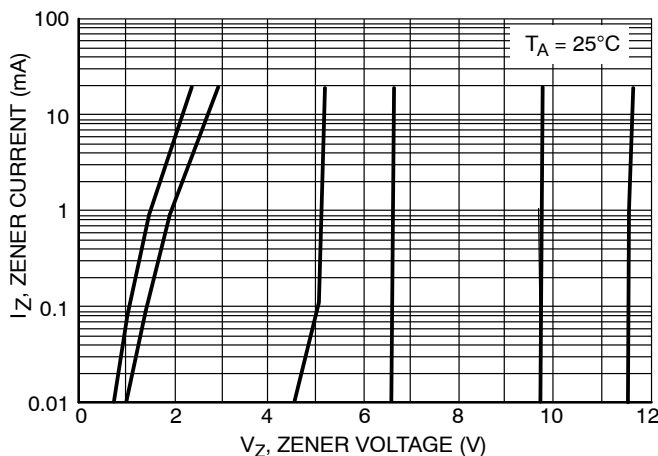


Figure 9. Zener Voltage versus Zener Current (V_Z Up to 12 V)

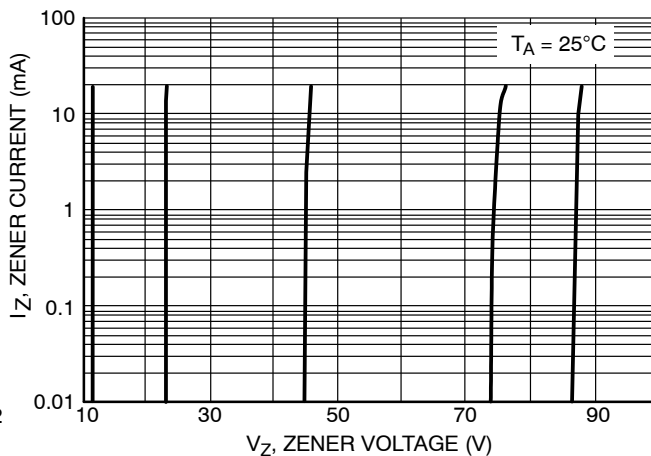


Figure 10. Zener Voltage versus Zener Current (12 V to 91 V)

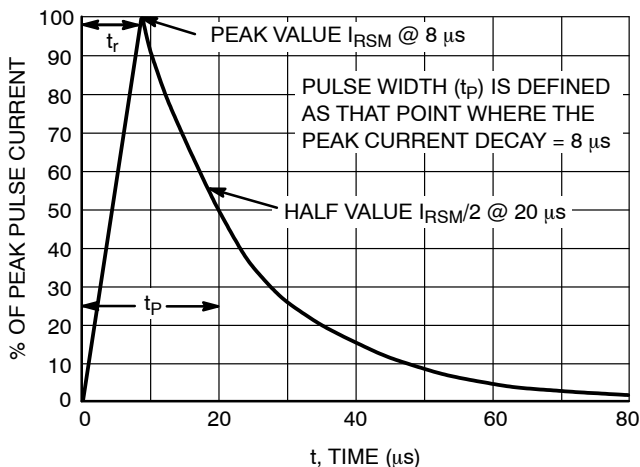
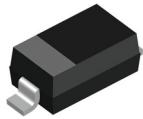


Figure 11. 8 × 20 μs Pulse Waveform

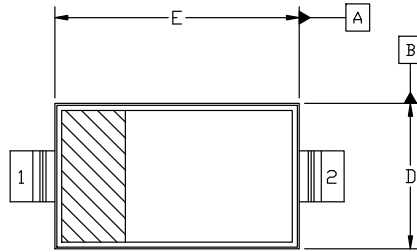
MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

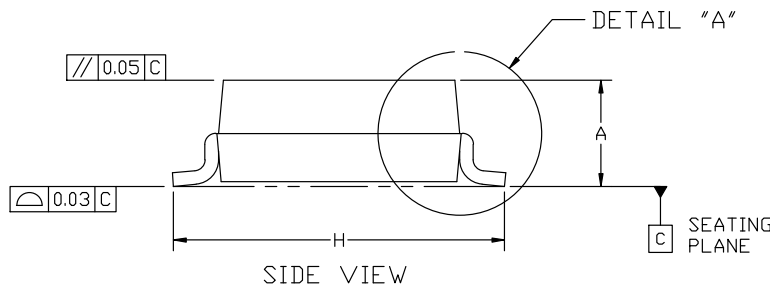


SOD-123 2L 1.60x2.69x1.16
CASE 425
ISSUE H

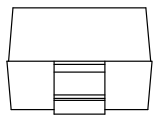
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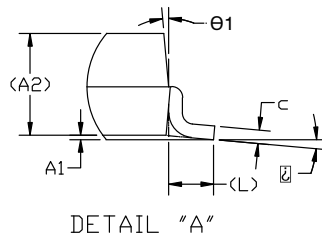
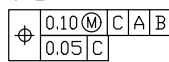
TOP VIEW



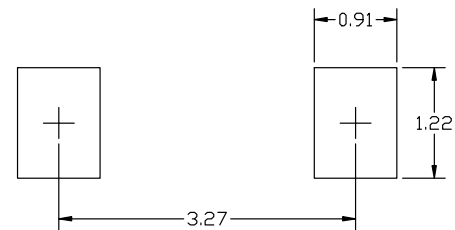
SIDE VIEW



END VIEW



DETAIL "A"



RECOMMENDED MOUNTING FOOTPRINT
 *For additional information on or Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference manual SOLDERM/D.

NOTES:

1. DIMENSION AND TOLERANCING PER ASME Y14.5M, 2018
2. CONTROLLING DIMENSION: MILLIMETERS

| DIM | MILLIMETER | | |
|-----|------------|------|------|
| | MIN. | NOM. | MAX. |
| A | 0.94 | 1.17 | 1.35 |
| A1 | 0.00 | 0.05 | 0.10 |
| A2 | 1.16 REF. | | |
| b | 0.51 | 0.61 | 0.71 |
| c | - | - | 0.15 |
| D | 1.40 | 1.60 | 1.80 |
| E | 2.54 | 2.69 | 2.84 |
| H | 3.56 | 3.68 | 3.86 |
| L | 0.25 REF. | | |
| ∠ | 0° | | 10° |
| θ1 | 0° | | 10° |

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
 M = Date Code
 ■ = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

STYLE 1:
 PIN 1. CATHODE
 2. ANODE

| | | |
|-------------------------|----------------------------------|--|
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